

Specification for TFT

AFC8001280A0-10.1INTM-I

Revision A

А	Orient Display
FY	ТFT Туре
480272	Resolution 800 x 1280
A0	Serial A0
10.1	10.1", Module Dimension 143.0x228.6x2.71 mm
1	IPS Display
Ν	Top: -20~+70°C; Tstr: -30~+80°C
Т	Transmissive
М	Medium Brightness, 600cd/m2
1	MIPI interface
1	No Touch Panel
1	ILI9881 or Compatible









Revision History

Date	Rev.	Description	Note	Page
2023-05-10	A	New issue		

С	on	Ite	nts

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1. Features

Item	Standard Value
Display Type	800(RGB)*1280 Dots
LCD Type	Normal black, Transmissive
Screen Size(inch)	10.1
Viewing Direction	All o'clock
Backlight	27pcs White LED
Weight	180.5g
Interface	MIPI
Other(controller/driver IC)	IL19881C

2. Mechanical Specifications

Item	Standard Value	Unit
Outline Dimension	143.0(L)*228.6(W)*2.71(T)	mm
Active Area	135.36(L)*216.58(W)	mm
Dots Pitch	0.1692(L)*0.1692(W)	mm

3. Absolute Maximum Ratings

Item	Symbol	Condition	Min.	Max.	Unit
Power Supply Voltage 1	V _{DD}	-	-0.3	3.8	V
Input Voltage	VIN	-	-0.5	VDDI+0.3	v
HS Input Voltage	VHSIN	-	-0.3	1.65	V
Operating Temperature	Тор	-	-20	70	°C
Storage Temperature	Т _{sт}	-	-30	80	°C
Humidity	-	Ta≦40℃	-	90	RH

4. DC Electrical Characteristics

Item	Symbol	Condition	Min.	Тур.	Max.	Unit
Analog operating Voltage	V _{ci}	Operating Voltage	2.5		6.6	V
Digital operating Voltage	V _{DDI}		1.65		6.6	V
Logic High level input Voltage	VIH		0.7*V _{DDI}		V _{DDI}	V
Logic Low level input Voltage	VIL		-0.3		0.3*V _{DDI}	V
Logic High level output Voltage TE LEDPWM	V _{OH}	IOH = -1.0mA	0.8*V _{DDI}		V _{DDI}	V
"L" Output Voltage	V _{OL}	IOL = +1.0mA	0		0.2*V _{DDI}	V
Supply Current	I _{DD}	-	25	50	100	mA
Gate Driver High voltage	VGH			15		V
Gate Driver Low voltage	VGL			-11		V
Analog Power supply voltage	AVDD/AVEE			5/-5		V

5. Optical Characteristics

lte	m	Symbol	Conditions	Min.	Тур.	Max.	Reference
	Тор	ΘΤ		75deg.	80deg.		
	Bottom	ΘΒ	0>10	75deg.	80deg.		Notes 1 & 2
View Angle	Left	ΘL	C <u>≥</u> 10	75deg.	80deg.		Notes 1 & 2
	Right	ΘR		75deg.	80deg.		
	White	Х		0.261	0.301	0.341	
	VVIIILE	Y		0.294	0.334	0.374	
	Ded	Х		0.585	0.625	0.665	
0.5 + 4	Red	Y	TA=25° C Θx, ΘY=0°	0.318	0.358	0.398	Notes 5
CIE *1	Green	Х		0.284	0.324	0.364	
		Y		0.545	0.585	0.625	
	Blue	Х		0.107	0.147	0.187	
	Diue	Y		0.087	0.127	0.167	
Unifo	rmity	U	lf=180mA	70%			Note 4
Contras	st Ratio	Cr	$\theta = \emptyset = 0^{\circ}$	800	1000		Note 3
Surface Brightness		L	Ø = 0°	400cd/m2	600cd/m2		Note 3 & 4
Respons (TR+	· TF)	TR+TF	TA=25° C ∅ = 0°		30ms		Note 2

*1: This value will be changed while mass product.







Note 4. Definition of Surface Luminance, Uniformity. (Ref Fig1) Surface Luminance: LV=average (LP1:LP9)

Uniformity=Minimal (LP1:LP9)/Maximal (LP1:LP9)*100%

Color Coordinate: The test condition is at IF current of backlight and measured on the surface of LCD module.

Note 5. CIE(x, y) chromaticity is the Center point value. (Ref Fig1)



6. Backlight Characteristics

ltem	Symbol	Conditions	Min.	Тур.	Max.	Unit
Forward Voltage	VF	lf=180mA	17.4		18.6	V
Forward Current	lF			180mA		mA

7. Touch Panel Characteristics NONE

8. Interface Pin Description TFT Interface Pin Description

Pin No.	Symbol	Function
1	LED+	Backlight Anode
2	LED+	Backlight Anode
3~8	NC	No connection
9	LED-	Backlight Cathod
10	LED-	Backlight Cathod
11	GND	Ground
12~13	NC	No connection
14	LCD PWM	LCD backlight control PWM output pin.
15	LCD_ID	ID pin
16	GND	Ground
17~18	NC	No connection
19	GND	Ground
20	DSI D3+	MIPI Data Bus
21	DSI_D3-	MIPI Data Bus
22	GND	Ground
23	DSI_D2+	MIPI Data Bus
24	DSI_D2-	MIPI Data Bus
25	GND	Ground
26	DSI_CLK+	MIPI Data Bus
27	DSI_CLK-	MIPI Data Bus
28	GND	Ground
29	DSI_D1+	MIPI Data Bus
30	DSI_D1-	MIPI Data Bus
31	GND	Ground
32	DSI_D0+	MIPI Data Bus
33	DSI_D0-	MIPI Data Bus
34	GND	Ground
35	NC	No connection
36	LCD_RST	LCD Reset signal.
37	GND	Ground
38	LCD_VDD	Power supply
39	LCD_VDD	Power supply
40	NC	No connection

9. Block Diagram of Display





10. Count Drawing

11. Timing Characteristics

Please references ILI9881C data sheet

12. Reliability

	Cinability			
NO	Item	Test 0	Condition	
1	High Temperature Storage	Storage at 80 \pm 2°C 24 hrs Surrounding temperature, then storage at normal condition 4hrs		
2	Low Temperature Storage	Storage at -30 \pm 2°C 24 hrs Surrounding temperature, then storage at normal condition 4hrs		
3	High Temperature Operation	Operation at 70 ± 2°C 24 hrs		
4	Low Temperature Operation	Operation at -20 ± 2°C 24 hrs		
5	High Temperature /Humidity Operating	Operation at $60 \pm 2^{\circ}$ C, 90% RH 96 hi temperature, then storage at normal	condition 4hrs.	
6	Thermal shock (non-operation)	(60mins) (10	25°C → 70°C Imins) (60mins) Cycle	
7	Mechanical Test	Freq.: 10-55Hz Max. Acceleration: 5G X.Y.Z. each direction For 10 mines. Drop them through 50cm height to strike horizontal plane		
8	ESD Test	Air Discharge: Apply +/-8KV with 5 timesContact Discharge: Apply +/-8KV with 5 timesDischarge for each polarity +/-Discharge for each polarity +/-1. Temperature ambiance: 15°C~35°C2. Humidity relative: 30%~60%3. Energy Storage Capacitance(Cs+Cd): 150pF+/-10%4. Discharge Resistance(Rd): 330Ω+/-10%5. Discharge, mode of operation:Single Discharge (time between successive discharges at least 1 sec)		
Note	1 For humidity test_DI wate	(Tolerance if the output voltage indic er should be used		
 Note 1. For humidity test, DI water should be used Inspection Standard: Inspect after 1-2hrs storage at room temperature, the sample shall be free from the following defects: Air bubble in the LCD Seal Leakage Non-display Missing Segment Glass Crack IDD is greater than twice initial value Others as per QA Inspection Criteria Note 2. No defect is allowed after testing. Note 3. ESD should be applied to LCD glass panel, not other areas (such as on IC and so on) IDD should be within twice initial value. In case of malfunction defect caused by ESD damage, if it would be recovered to normal state after resetting, it would be judged as a good part. 				
Note 4. Only upon request.				

Note 5. ODNA carried out a high temperature and high humidity test at 60 ° C / 90% for 240 hours as an ability measurement of this product. As a result, it was confirmed that no abnormality occurred in the product. No indication or external shape abnormality. No FPC corrosion deterioration. Please refer to the official test report on the separate sheet. This result is only for confirming the ability of these 10pcs samples, and does not guarantee the reliability can always meet the above specifications.

13. Specification of Quality Assurance

13.1 Purpose

This standard for Quality Assurance assures the quality of LCD module products supplied to customer by ODNA

oy odna

13.2 Standard for Quality Test

ODNA performs the following tests to ensure the quality of product before shipment.

Sampling Plan:

GB/T2828.1-2003. Single sampling, Normal Inspection Level II.

Single sampling, normal inspection

Sampling Level:

Minor Defect: AQL 0.65%

Major Defect: AQL 0.15%.

Reliability Test:

Detailed requirement refer to Reliability Test Specification.

Nonconforming Analysis & Disposition

Nonconforming analysis

Customer should provide overall information of non-conforming sample for their complaints.

After receipt of detailed information from customer, the analysis of nonconforming parts usually should be finished in one week.

If ODNA can not finish the analysis on time, customer will be notified with the progress status. Disposition of nonconforming:

Non-conforming product over ppm level will be replaced.

The cause of non-conformance will be analyzed. Corrective action will be discussed and implemented.

Agreement Items

ODNA and customer shall negotiate if the following situation occurs

There is any discrepancy in standard of quality assurance.

Additional requirement to be added in product specification.

Any other special problem.

13.3 Standard of the Product Visual Inspection

Appearance inspection

The normal inspection must be under illumination no less than 800lux, and the distance of view must be between 30cm and 45cm;

When inspect the model of transmissive product, back light must be lighted.

The visual viewing angle should be 45° from the vertical line without reflection shine or follows customer's viewing angle specifications.



Definition of area(refer to product drawing)





Basic principle:

According to IPC standards if standard is not described in specification.

A set of sample to indicate the limit of acceptable quality level must be discussed by both ODNA and customer when there is any dispute happened.

New item must be added on time when it is necessary.

13.4 Inspection Specification

No.	Item	Criteria (Unit: mm)						
Func	Functional							
01	LC leakage	LC leakage	Reject	Maj				
02	Non-display	Non-display	Reject	Maj				
03	Missing segment/ Missing character, dot or icon.		Reject	Maj				

04	Exceeded dot/line/segment /Distortion			Reject	Maj	
05	Dim Display	part of figures disp obvi	As the samples co each othe	Min		
06	Wrong view angle	View angle is di	fferent from spec.	Reject	Maj	
07	Not light		ht not work ED not light	Reject		Maj
08	Backlight Luminance \ uniformity	According to the pro	oduct specification or samples	Reject		Min
09	Backlight Color		oduct specification or samples	Reject		Min
10	CTP no response	CTP touch	no response	Reject		Maj
11	Connection failure	FPC gold fi	nger damage	Reject		Maj
Арр	earance					
01	Black and white spot, Red, blue and green spot Dent Foreign material (Round type)	$\phi = (a + b)/2$ Distance between 2 defects should more than 10 mm apart.	Size(mm) $\phi \le 0.3$ $0.3 < \phi \le 0.5$ $0.50 < \phi \le 0.8$ $\phi > 0.80$	AreaAcc. QZoneZoneABIgnore4206		Min
02	Black and White line Scratch Foreign material (Line type) (Min)	W Length (mm) / L ≤ 5 L ≤ 3 Distance between 2	$W \leq 0.03$ $0.03 < W \leq 0.05$ $0.05 < W \leq 0.1$ $W > 0.10$ Total defects should more th	2 0 6	Zone C NC NC NC NC NC	Min

03		Diameter: Φ(mm)		Accept Qty				
				Zone A	Zone B	ZoneC	-	
	Polarizer concave	Φ<0.3mm	Ignore				Min	
	and convex/bubbles	0.3mm<Ф≤0.5mm	5		Ignora	Ignoro		
		0.5mm<Φ≤0.8mm	2		Ignore	Ignore		
		Φ>0.8mm	Una	cceptable]			
		Distance between 2 defects should more than 10mm apart.						
		*A dot is defined as a single pixel (either red, green, or b within a pixel. Definition of Bright dots: D that can be seen through 6 % filter.	olue) oots		Allow			
		Bright dots(Min)			3			
		Adjacent bright dots			1			
	Bright/Dark dots, lines, Pixel defects	Dark dots 5			-			
		Adjacent dark dots			2 5% ND filter distance, if			
		Mura(50% GERY)		Judge by 6	5% ND filter distance, if		-	
04		Dark or Bright Lines 0						
		Blank pixel/ Missing pixe Remark: One pixel consists of dot(Sub-pixel=Dot)		oixels, includ	Not allow ding R,G and	d B	Min	
		Note 1 Bright dot is defined through 6	% tran	smission NE) filter as fol	llowing:		
		ND Filter TFT-LCD Panel Defects on the black Matrix, or		 IFT-LCD Panel	lcm	er Position		
05	TFT Glass cracked	defect counted. Symbols X: Chip length Z: Chip thickness T: Glass thickness L: Electrode pad length	K:	: Chip width Seal width LCD side le			Min	
	Cracked	a) General glass chip 1. Chip on panel surfac	e and o	crack betwee	en panels			



06	Discolor/rainbow	Discolor between the LCDs or in the same LCD	Refer to the limit samples signed by customers or Casil	Min
	FPC/FFC /TAB/HSC	Connect surface oxidation	Not allow	Maj
		Etching/damage /distortion	Not exceed 1/3 width of wire	Min
07		Connect surface contamination /foreign material	Width & length of electric foreign material could not exceed the witdth of 2 pins	Min
		Connect surface scratch	The scratch depth not exceed 1/2 thickness of gold layer.	Min
		Copper/protective film/base board film separate	Not allow	Maj
		Others: FPC follow IPC-6013A standard.		
	Soldering	Cold soldering, short soldering	Reject	Min
0.0		Not enough solder paste	Solder paste area < 75% solder pad area Solder paste area < 75% component solder point Solder paste height <1/2 component height	Min
08		FPC Pin deviation	Deviation area > 1/3 Solder pad	Min
		Others: Follow IPC	C-A-610E standard	

09	COG silicon coating	 a) Not exceed the surface of top polarizer, LCD left/right edges. Cover fully ITO, IC and the juncture of HSC/FPC and LCD. b) No visible non-metal foreign material and metal material in coating c) Entrapped air bubble isn't permissible to exist on the juncture of coating glue and pins of LCD. d) Bubbles or pinhole of silicon coating should Φ≤2mm e) The silicon should cover all around the IC and not gap in between silicon and side of IC, lack of coating on top of IC can be accepted 	Min	
10	CTP Cover Glass	Symbols X: Chip length Z: Chip thickness Chip on corner or edgeY: Chip width $I = I = I = I = I = I = I = I = I = I =$	Min	
11	Glass warping	$\begin{tabular}{ c c c c } \hline Product diagonal length (mm) & Warpage range (mm) \\ \hline L \le 10 & 0.05 \\ \hline 10 < L \le 30 & 0.1 \\ \hline 30 < L \le 100 & 0.2 \\ \hline 100 < L \le 300 & 0.4 \\ \hline 300 < L \le 1000 & 0.6 \\ \hline 1000 < L \le 3000 & 0.8 \\ \hline \end{tabular}$	Maj	
12	Color of silk Screen	Refer to limit sample or measurement data base on SPEC	Min	
13	Backlight	 Spots or scratches that appear when light must be judged using LCD glass spot, line and contamination standards. Brightness and Chromaticity can't be out of specification. 		
14	Bezel	a) No rust, distortion on the Bezel.b) No visible fingerprints, stains or other contamination.	Min	
		Dent $1 \text{ mm} \diamond 0.5 \text{ mm}$, Accept	Min	

		2		
		Ø≤0.5 mm	ignore	Min
	Exposed base metal material on front surface	Ø≤0.5 mm ,2pcs	Accept	Min
	Exposed base meta material on side	Dot : Ø≤1.0mm, Line: L≤2.0mm、 W≤0.5mm	Accept	Min
	Scratched	Exposed base metal material	Reject	Min

13.5 RoHS Compliance

The product is compliant to RoHS.

14. Package Specification

TBD

15. Precaution for Using LCD Module

15.1 Handing Precaution

- 15.1.1 The display panel is made of glass and polarizer. As glass is fragile. It tends to become or chipped during handing especially on the edges. Please avoid dropping or jarring. Do not subject it to a mechanical shock by dropping it or impact.
- 15.1.2 If the display panel is damaged and the liquid crystal substance leaks out, be sure not to get any in your mouth. If the substance contacts your skin or clothes, wash it off using soap and water.
- 15.1.3 Do not apply excessive force to the display surface or the adjoining areas since this many cause the color tone to vary. Do not touch the display with bare hands, This will stain the display area and degraded insulation between terminals(some cosmetics are determined to the polarizer)
- 15.1.4 The polarizer covering the display surface of the LCD module is soft and easily scratched. Handle this polarizer carefully. Do not touch, push or rub the exposed polarizer with anything harder than an HB pencil lead (glass, tweezers, etc.).Do not put or attach anything on the display area to avoid leaving marks on it. Condensation on the surface and contact with terminals due to cold will damage, stain or dirty the polarizer. After products are tested at low temperature they must be warmed up in a container before coming in to contact with room temperature air.
- 15.1.5 If the display surface becomes contaminated, breathe on the surface and gently wipe it whit a soft dry cloth. If it is heavily contaminated, moisten cloth with one of the following solvents,-Isotropy alcohol or Ethyl alcohol; do not scrub hard to avoid damaging the display surface.
- 15.1.6 Solvents other than those above-mentioned madly damage the polarizer. Especially, do not use the following: water, Ketone, Aromatic solvents. Wipe off saliva or water drops immediately, contact with water over a ling period of time may cause deformation or color fading. Avoid contact with oil and fats.
- 15.1.7 Exerciser care to minimize corrosion of the electrode. Corrosion of the electrodes is accelerated by water droplets, moisture condensation or current flow in a high-humidity environment.

- 15.1.8 Install the LCD module by using the mounting holes. When mounting the LCD module make sure it is free of twisting, warping and distortion. In particular, do not forcibly pull or bend the I/O cable or the backlight cable.
- 15.1.9 Do not attempt to disassemble or process the LCD module.
- 15.1.10 NC terminal should be open. Do not connect anything.
- 15.1.11 If the logic circuit power is off, do not apply the input signals.
- 15.1.12 Electro-Static Discharge control, since this module uses a CMOS LSI, the same careful attention should be paid to electrostatic discharge as for an ordinary CMOS IC. To prevent destruction of the elements by static electricity, be careful to maintain an optimum work environment.
- 15.1.13 Since LCM has been assembled and adjusted with a high degree of precision, avoid applying excessive shocks to the module or making any alterations or modifications to it.

15.2 Storage Precaution

- 15.2.1 Store them in a sealed polyethylene bag. If properly sealed, there is no need for the desiccant.
- 15.2.2 Store them in a dark place. Do not expose to sunlight or fluorescent light, keep the temperature between 0°C and 35°C, and keep the relative humidity between 40% RH and 60% RH.
- 15.2.3 The polarizer surface should not come in contact with any other objects (we advise you to store them in anti-static electricity container in which they were shipped).
- 15.2.4 During shipment, please handle with care. The packaging bag can not be broken, step on trap. Packaging Carton layer height can not be over two meters.
- 15.2.5 The transportation process should pay attention to the waterproof and moisture-proof measures. Product can not be watering. Ethylene sealed bags can not be unsealed.
- 15.2.6 Liquid crystals solidify under low temperature (below the storage temperature range) leading to defective orientation or the generation of air bubbles (black or white). Air bubbles may also be generated if the module is subject to a low temperature.
- 15.2.7 If the LCD modules have been operating for a long time showing the same display patterns, the display patterns may remain on screen as ghost images and a slight contrast irregularity may also appear. A normal operating status can be regained by suspending use for some time. It should be noted that this phenomenon does not adversely affect performance reliability.
- 15.2.8 To minimize the performance degradation of the LCD modules resulting from destruction caused by static electricity etc.,

15.3 Using LCD Modules

- 15.3.1 The hole in the printed circuit board is used to fix LCM. Attend to the following items when installing the LCM. Cover the surface with a transparent protective plate to protect the polarizer and LC cell.
- 15.3.2 When assembling the LCM into other equipment, the spacer to the bit between the LCM and the

fitting plate should have enough height to avoid causing stress to the module surface, refer to the individual specifications for measurements. The measurement tolerance should be +/-0.1mm.

- 15.3.3 Precaution for assemble the module with BTB connector; Please note the position of the male and female connector position.
- 15.3.4 Precaution for soldering the LCM, Manual soldering temperature 300+/-20°C , time is 3~5S.
- 15.3.5 If soldering flux is used, be sure to remove any remaining flux after finishing to soldering operation (This does not apply in the case of a non-halogen type of flux). It is recommended that you protect the LCD surface with a cover during soldering to prevent any damage due to flux spatters.
- 15.3.6 When soldering the electroluminescent panel and PC board, the panel and board should not be detached more than three times. This maximum number is determined by the temperature and time conditions mentioned above, though there may be some variance depending on the temperature of the soldering iron.
- 15.3.7 When remove the electroluminescent panel from the PC board, be sure the solder has completely melted, the soldered pad on the PC board could be damaged.

15.4 Precautions for Operation

- 15.4.1 Viewing angle varies with the change of liquid crystal driving voltage (VLCD). Adjust VLCD to show the best contrast.
- 15.4.2 It is an indispensable condition to drive LCD within the specified voltage limit since the higher voltage then the limit cause the shorter LCD life. An electrochemical reaction due to direct current causes LCD undesirable deterioration, so that the use of direct current drive should be avoid.
- 15.4.3 Response time will be extremely delayed at lower temperature than the operating temperature range and on the other hand at higher temperature LCD show dark color in them. However those phenomena do not mean malfunction or out of order with LCD which will come back in the specified operating temperature.
- 15.4.4 If the display area is pushed hard during operation, the display will become abnormal. However, it will return to normal if it is turned off and back on.
- 15.4.5 Slight dew depositing on terminals is a cause for electro-chemical reaction resulting in terminal open circuit. Usage under the maximum operating temperature, 50%RH or less is required.
- 15.4.6 Input logic voltage before apply analog high voltage such as LCD driving voltage when power on. Remove analog high voltage before logic voltage when power off the module. Input each signal after the positive & negative voltage becomes stable.
- 15.4.7 Please keep the temperature within the specified range for use and storage. Polarization degradation, bubble generation or polarizer peel-off many occur with high temperature and high humidity.

15.5 Safety

- 15.5.1 It is recommended to crush damaged or unnecessary LCD into pieces and wash them off with solvents such as acetone and ethanol, which should later be burned.
 - 15.5.2 If any liquid leaks out of a damaged glass cell and comes in contact with the hands, wash off

thoroughly with soap and water.

15.6 Limited Warranty